



## Android BSP Version 0.9 Release Notes for the Open-Q™ 845 HDK Hardware Development Kit **Binary-only release**

[Document: ITC-01IMP1335-RN-009 Revision: 1.0]

Your use of this document is subject to and governed by those terms and conditions in the Intrinsyc Purchase and Software License Agreement for the Snapdragon 845 (SDA845) based Open-Q™ Development Kit, which you or the legal entity you represent, as the case may be, accepted and agreed to when purchasing a Development Kit from Intrinsyc Technologies Corporation (“**Agreement**”). You may use this document, which shall be considered part of the defined term “Documentation” for purposes of the Agreement, solely in support of your permitted use of the Development Kit under the Agreement. Distribution of this document is strictly prohibited without the express written permission of Intrinsyc Technologies Corporation and its respective licensors, which they can withhold, condition or delay in its sole discretion.

Intrinsyc is a trademark of Intrinsyc Technologies Corporation, registered in Canada and other countries.

Qualcomm and Snapdragon are trademarks of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names used herein may be trademarks or registered trademarks of their respective owners.

This document contains technical data that may be subject to U.S. and international export, re-export, or transfer (“export”) laws. Diversion contrary to U.S. and international law is strictly prohibited.

## IDENTIFICATION

Document Title	Android BSP Version 0.9 Release Notes for the Open-Q™ 845 HDK Hardware Development Kit
Document Number	ITC-01IMP1335-RN-009
Version	1.0
Date	March 23, 2018

# Table of Contents

<b>1.</b>	<b>INTRODUCTION.....</b>	<b>4</b>
1.1	Purpose .....	4
1.2	Scope.....	4
1.3	Intended Audience .....	4
<b>2.</b>	<b>DOCUMENTS .....</b>	<b>5</b>
2.1	Applicable Documents.....	5
2.2	Reference Documents .....	5
<b>3.</b>	<b>DEVELOPMENT KIT OVERVIEW .....</b>	<b>6</b>
3.1	Introduction.....	6
3.2	Development Device Notice.....	6
<b>4.</b>	<b>HARDWARE CONFIGURATION.....</b>	<b>7</b>
<b>5.</b>	<b>SOFTWARE RELEASE FUNCTIONAL DESCRIPTION .....</b>	<b>8</b>
5.1	Introduction: .....	8
5.2	Software Release Identification .....	8
5.3	Software Release Package .....	8
5.4	BSP history .....	9
5.4.1	BSP Release 0.9 - Android 8.1.0 / Oreo™.....	9
<b>6.</b>	<b>KNOWN ISSUES .....</b>	<b>10</b>

# 1. INTRODUCTION

## 1.1 Purpose

This document describes functionalities and any known issues for the Android BSP Software Release 0.9 for the Intrinsic Open-Q 845 HDK Development Kit.

To access the documentation please visit <http://support.intrinsic.com>

## 1.2 Scope

This document describes the following for the Open-Q 845 HDK Development Kit Software Release 0.9:

- Supported software capabilities and features
- Known issues

## 1.3 Intended Audience

This document is intended for Open-Q 845 HDK Development Kit users.

## 2. DOCUMENTS

This section lists any parent and supplementary documents for these Release Notes. Unless stated otherwise, applicable documents supersede this document and reference documents provide background and supplementary information.

### 2.1 Applicable Documents

REFERENCE	AUTHOR	TITLE
A-1	Intrinsyc	Intrinsyc Purchase and Software License Agreement for the Open-Q™ 845 Development Kit <a href="https://www.intrinsyc.com/legal-terms/qualcomm-terms.html">https://www.intrinsyc.com/legal-terms/qualcomm-terms.html</a>

### 2.2 Reference Documents

REFERENCE	DOCUMENT NUMBER	AUTHOR	TITLE
R-1	01IMP1335-QSG-001	Intrinsyc	Intrinsyc Open-Q 845 Development Kit Quick Start Guide
R-4	01IMP1335-UG-001	Intrinsyc	Intrinsyc Open-Q 845 Development Kit User Guide

## 3. DEVELOPMENT KIT OVERVIEW

### 3.1 Introduction

The Open-Q 845 HDK Development Kit provides a platform on which customers can develop, test, and deploy their software and peripheral solutions around the Qualcomm Snapdragon 845 processor (SDA845).

The kit is also a completely functional platform for application developers and OEMs to evaluate, develop, test, and deploy applications that utilize the Qualcomm Snapdragon technology in a cost-effective manner.

### 3.2 Development Device Notice

This development device contains RF/digital hardware and software intended for engineering development, engineering evaluation, or demonstration purposes only and is intended for use in a controlled environment. This device is not being placed on the market, leased or sold for use in a residential environment or for use by the general public as an end user device.

This development device is not intended to meet the requirements of a commercially available consumer device including those requirements specified in the European Union directives applicable for Radio devices being placed on the market, FCC equipment authorization rules or other regulations pertaining to consumer devices being placed on the market for use by the general public.

This development device may only be used in a controlled user environment where operators have obtained the necessary regulatory approvals for experimentation using a radio device and have appropriate technical training. The device may not be used by members of the general population or other individuals that have not been instructed on methods for conducting controlled experiments and taking necessary precautions for preventing harmful interference and minimizing RF exposure risks. Additional RF exposure information can be found on the FCC website at <http://www.fcc.gov/oet/rfsafety>.

## **4. HARDWARE CONFIGURATION**

This software release was tested on the Open-Q 845 HDK Development Kit. This includes the CPU board, Carrier board, LCD with multi-touch (optional), and camera board (optional).

The Open-Q 845 HDK Development Kit from Intrinsic is delivered to customers pre-programmed with an Android image.

## **5. SOFTWARE RELEASE FUNCTIONAL DESCRIPTION**

### **5.1 Introduction:**

This section describes the features and capabilities of this Android BSP software.

### **5.2 Software Release Identification**

This software release version is based on Qualcomm release with adaptations and customizations for use with the Open-Q 845 HDK Development Kit.

### **5.3 Software Release Package**

This software release consists of the following items:

- Binaries – this version is a binary-only release that is delivered on the development kit.



## 5.4 BSP history

### 5.4.1 BSP Release 0.9 - Android 8.1.0 / Oreo™

- Initial release
- Linux Kernel Version: 4.9.65+
- CAF Tag: caf\_AU\_LINUX\_ANDROID\_LA.UM.6.3.R4.08.01.00.440.016
- LCD panel support (Touch support not available)
- microSD card as file storage (up to 32GB tested)
- Bluetooth
  - HID
  - File Transfer (with Android Phone)
- BLE
- Debug UART interface via USB serial port
- Micro C USB support for adb interface
- USB Host 2.0 support for human interface devices (mouse/keyboard)
- Battery operation support

## 6. KNOWN ISSUES

The following list identifies the known issues in this software release. Future releases will be posted as these issues are resolved.

- Touch is not supported
- HDMI is not supported
- WIFI is not supported
- GPS is not supported
- Audio is not supported
- Media playback is not supported
- USB 2.0 does not support USB Flash
- Camera hardware is not tested
- Sensors are not tested
- Mounting storages over USB to PC (PTP/MTP/Mass storage) is not supported
- Video over micro C USB is not supported
- Device will not boot on DC power if battery is disconnected.
- Unlocking device using mouse is sometimes difficult. Easiest way to unlock is swiping phone application.

